

100-Pin FineLine Ball-Grid Array (FBGA) - Option 2 - Wire Bond

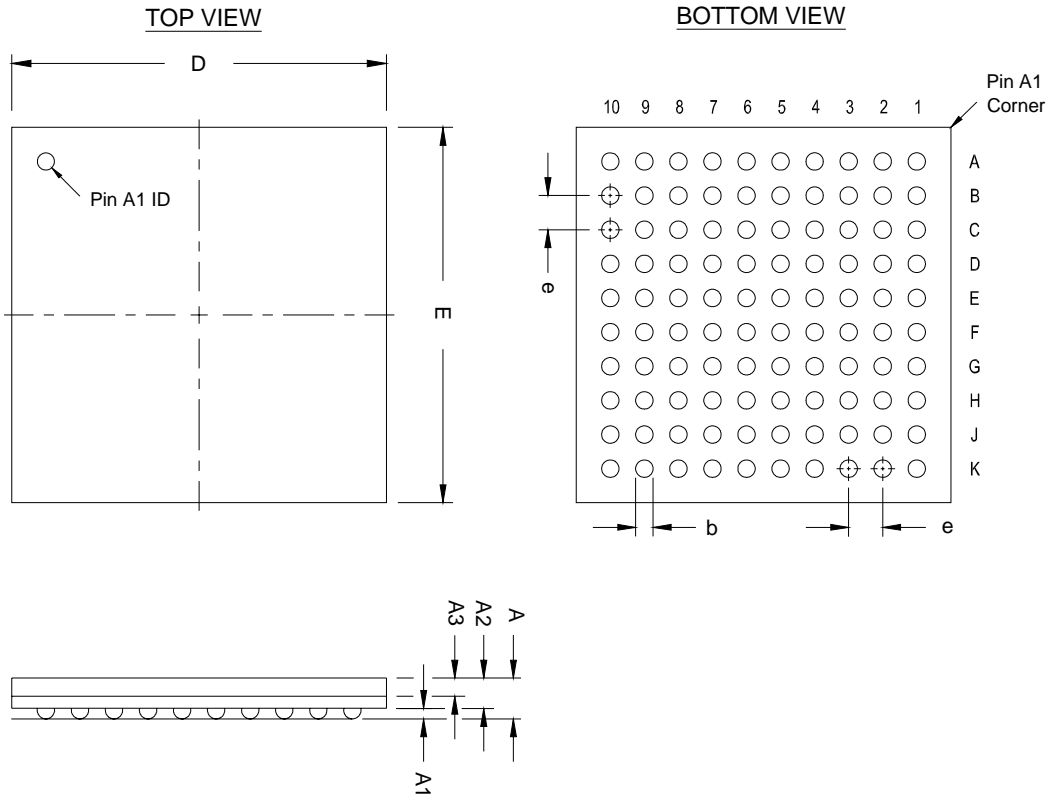
- All dimensions and tolerances conform to ASME Y14.5M – 1994.
- Controlling dimension is in millimeters.
- Pin A1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

Note: This POD is applicable to F100 packages of the MAX II device only.

Package Information	
Description	Specification
Ordering Code Reference	F
Package Acronym	FBGA
Substrate Material	BT
Solder ball composition	Regular: 63Sn:37Pb (Typ.) Pb-free: Sn:3Ag:0.5Cu (Typ.)
JEDEC Outline Reference	MO-192 Variation: DAC-1
Maximum Lead Coplanarity	0.008 inches (0.20mm)
Weight	0.6 g
Moisture Sensitivity Level	Printed on moisture barrier bag

Package Outline Dimension Table			
Symbol	Millimeters		
	Min.	Nom.	Max.
A	–	–	1.55
A1	0.25	–	–
A2	1.05 Ref		
A3	–	–	0.80
D	11.00 BSC		
E	11.00 BSC		
b	0.45	0.50	0.55
e	1.00 BSC		

Package Outline





101 Innovation Drive
San Jose, CA 95134
(408) 544-7000
<http://www.altera.com>

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